

Notice of References CitedApplication/Control No.
10/056,258Applicant(s)/Patent Under
Reexamination
NAKAGAWA ET AL.Examiner
Dexter TugbangArt Unit
3729

Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	L	US-			
	M	US-			

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	V	Illyefalvi et al, "Application of Laser Engraving for the Fabrication of Fine Resolution Printed Wiring Laminates for MCM-Ls", Electronic Components and Technology Conference, May 1997, pages 507-510.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.